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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of

Simon Leonard Rumer

Application No.: 10/567,377

Filed: February 7, 2006

For: IMPROVEMENTS TO PACKAGED HIGH FREQUENCY CERAMIC CIRCUITS

CIRCUITS

Group Art Unit: 3729

Examiner:

Confirmation No.: 6743

RESPONSE TO RESTRICTION REQUIREMENT

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

In an Official Action dated February 13, 2008, the Examiner has indicated that restriction to one of the following inventions is required under 35 U.S.C. § 121:

Group I: Claims 1-9 and 10-15, drawn to a method of assembling a package high frequency circuit module; and

Group II: Claim 9, drawn to a high frequency circuit module,

where Group I contains the following Species:

Species A: drawn to the stub walls projected from the internal surface of the substrate:

Species B: drawn to the stub walls projected from the upper planar surface of the substrate; and

Species C: drawn to the stub walls projected from the lower planar surface of the substrate.

Accordingly, Applicants provisionally elect Group I, Species A, the subject matter of Claims 1, 3, 5, 6, 9, 10, 12, 15, and 15, with traverse. Applicants submit